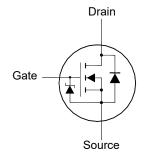
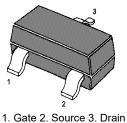
N-Channel Enhancement Mode MOSFET

Features

- Surface-mounted package
- Gate-Source Zener for ESD ruggedness
 - > 6KV Human Body Model
- Typical ESD Protection HBM Class 3A

Classification	Voltage Range(V)
0A	< 125
0B	125 to < 250
1A	250 to < 500
1B	500 to < 1000
1C	1000 to < 2000
2	2000 to < 4000
3A	4000 to < 8000
3B	≥ 8000





SOT-23 Plastic Package

Applications

- · Portable appliances
- · Battery management

Absolute Maximum Ratings (at Ta = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	25	V
Gate-Source Voltage	V _G s	8	V
Drain Current	I _D	220	mA
Peak Drain Current, Pulsed 1)	I _{DM}	1.6	Α
Total Power Dissipation 2)	P _{tot}	350	mW
Operating Junction and Storage Temperature Range	T _j ,T _{stg}	- 55 to + 150	°C

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient	ReJA	357 ²⁾ 275 ³⁾	°C/W

¹⁾ Pulse Test: Pulse Width ≤ 100 μs, Duty Cycle ≤ 2%,Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.



²⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad.

³⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.

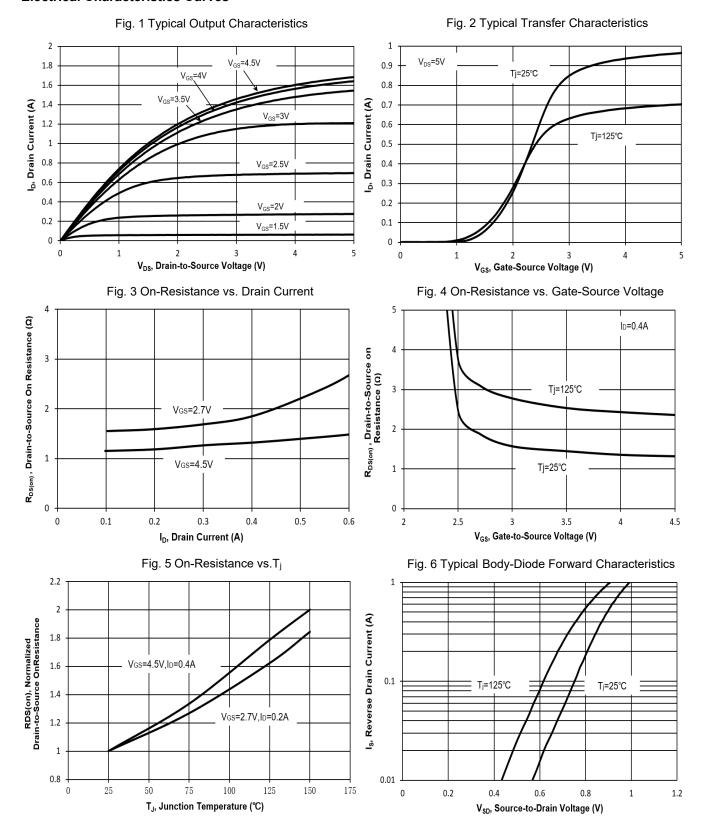
MMFTN301ZK

Characteristics at Ta = 25°C unless otherwise specified

Parameter	Symbol	Min.	Тур.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at I _D = 250 μA	V _{(BR)DSS}	25	-	-	V
Drain-Source Leakage Current at V _{DS} = 20 V	I _{DSS}	-	-	1	μA
Gate-Source Leakage Current at V _{GS} = 8 V	I _{GSS}	-	-	100	nA
Gate-Source Threshold Voltage at V_{DS} = V_{GS} , I_D = 250 μ A	V _{GS(th)}	0.7	-	1.1	V
Drain-Source On-State Resistance at V_{GS} = 4.5 V, I_D = 0.4 A at V_{GS} = 2.7 V, I_D = 0.2 A	R _{DS(on)}	- -	- -	4 5	Ω
DYNAMIC PARAMETERS					
Gate resistance at $V_{DS} = 0 \text{ V}$, f = 1 MHz	Rg	-	38	-	Ω
Forward Transconductance at V_{DS} = 5 V, I_D = 0.4 A	g FS	-	760	-	mS
Input Capacitance at $V_{DS} = 10 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	C _{iss}	-	51	-	pF
Output Capacitance at V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz	Coss	-	11	-	pF
Reverse Transfer Capacitance at V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz	Crss	-	8	-	pF
Gate charge total at V_{DS} = 25 V, I_D = 1 A, V_{GS} = 4.5 V	Qg	-	0.85	-	nC
Gate to Source Charge at V_{DS} = 25 V, I_D = 1 A, V_{GS} = 4.5 V	Q _{gs}	-	0.45	-	nC
Gate to Drain Charge at V_{DS} = 25 V, I_D = 1 A, V_{GS} = 4.5 V	Q_{gd}	-	0.3	-	nC
Turn-On Delay Time at V_{DD} = 10 V, I_D = 1 A, V_{GS} = 4.5 V, R_G = 51 Ω	t _{d(on)}	-	13	-	ns
Turn-On Rise Time at V_{DD} = 10 V, I_D = 1 A, V_{GS} = 4.5 V, R_G = 51 Ω	t _r	-	13	-	ns
Turn-Off Delay Time at V_{DD} = 10 V, I_D = 1 A, V_{GS} = 4.5 V, R_G = 51 Ω	t _{d(off)}	-	7.7	-	ns
Turn-Off Fall Time at V_{DD} = 10 V, I_D = 1 A, V_{GS} = 4.5 V, R_G = 51 Ω	t _f	-	4.6	-	ns
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at Is = 0.29 A	VsD	-	-	1.2	V
Body-Diode Continuous Current	ls	-	-	220	mA
Body Diode Reverse Recovery Time at I _S = 1 A, di/dt = 100 A / μs	t _{rr}	-	9	-	ns
Body Diode Reverse Recovery Charge at I _S = 1 A, di/dt = 100 A / μs	Qrr	-	3.7	-	nc



Electrical Characteristics Curves





Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

Ciss f=1MHz

Coss

Coss

Coss

V_{Ds}, Drain-Source Voltage (V)

Fig. 8 Drain-Source Leakage Current vs. T_j

10

V_{DS}=20V

0.01

0.01

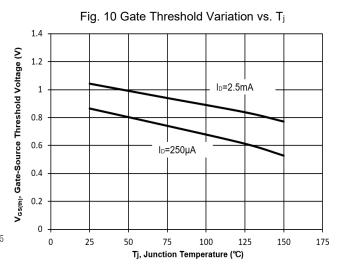
0.25

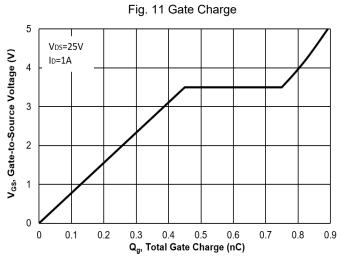
50

75

T_J, Junction Temperature (°C)

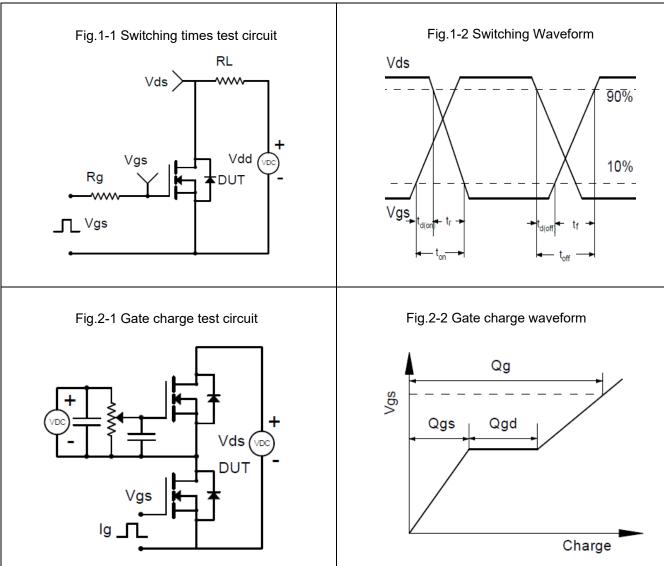
Fig. 9 V_{(BR)DSS} vs. Junction Temperature V_{DSS}, Drain-Source Breakdown Voltage (V) I⊳=250µA T_J, Junction Temperature (°C)







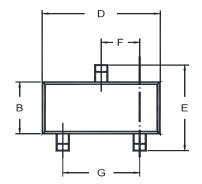
Test Circuits

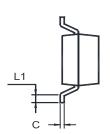


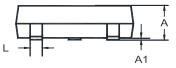


Package Outline (Dimensions in mm)

SOT-23

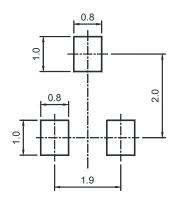






Unit	Α	A1	В	С	D	Е	F	G	Ш	L1
	1.20	0.100	1.40	0.19	3.04	2.6	1.02	2.04	0.51	0.2
mm	0.89	0.013	1.20	0.08	2.80	2.2	0.89	1.78	0.37	MIN

Recommended Soldering Footprint



Packing information

Dealer	Tape Width	Pit	tch	Reel	Size		
Package	(mm)	mm	inch	mm	inch	Per Reel Packing Quantity	
SOT-23	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000	

Marking information

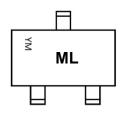
" ML " = Part No.

" YM " = Date Code Marking

" Y " = Year

" M " = Month

Font type: Arial



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